

Package : DIP

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1. Structure and materials

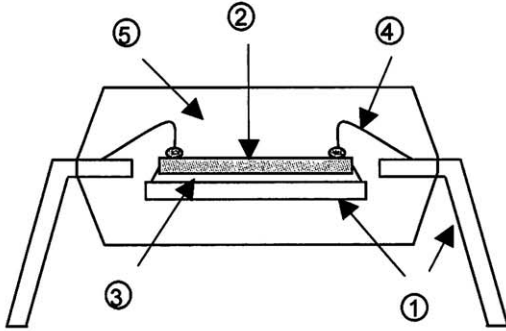


Fig. 1 Structure

| No. | Item | Materials |
|-----|------------|---|
| ① | Lead Frame | DIP28 : Alloy 42 (External lead : Pb free solder plating) except DIP28 : Cu-Alloy (External lead : Pb free solder plating) |
| ② | Die | Silicon |
| ③ | Die Attach | Ag Paste |
| ④ | Wire | Au |
| ⑤ | Molding | Epoxy Resin |

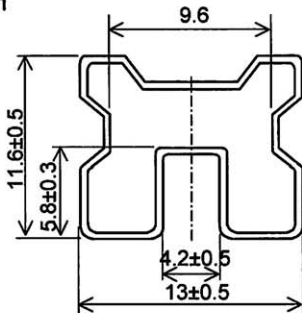
2. Packing information

2.1. Packing specification

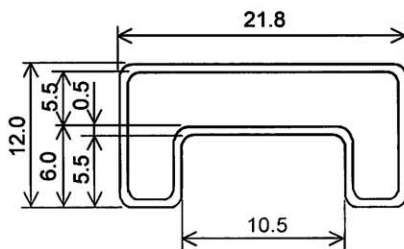
| | |
|-----------|---------------------------|
| Container | Tube |
| Quantity | See the table on page 3/3 |

2.2. Tube specification

DIP-T8
DIP14
DIP16
DIP18
DIP20
DIP22



DIP28



(all dimensions in mm)

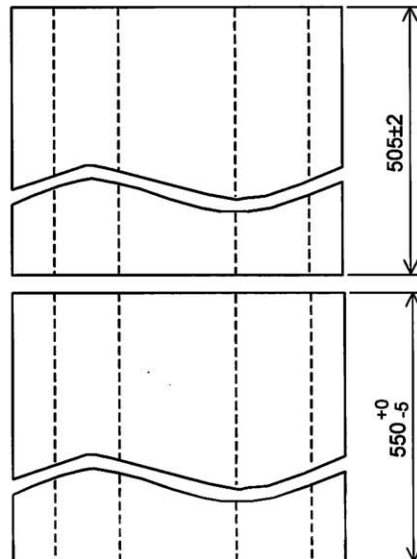


Fig. 2 Tube dimensions

2.3. Label for Box

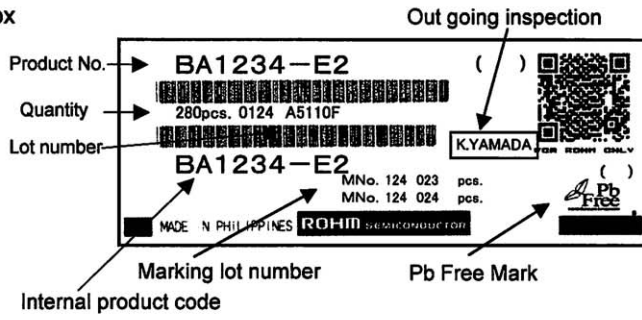


Fig. 3 Label example

2.4. Packing style

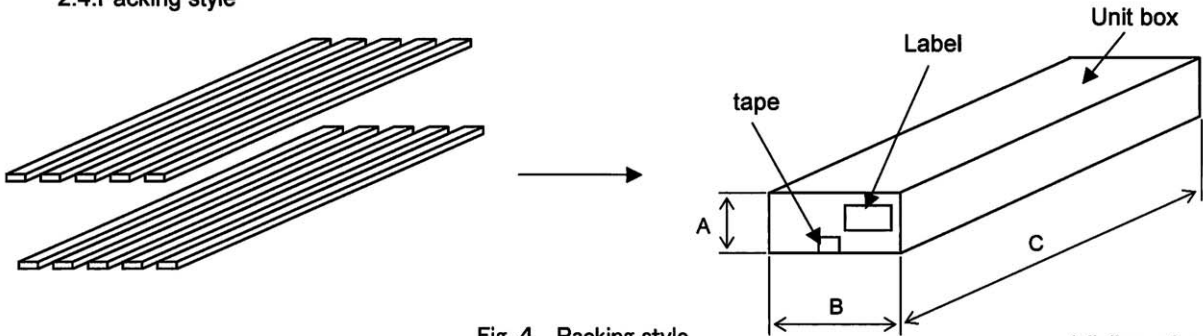
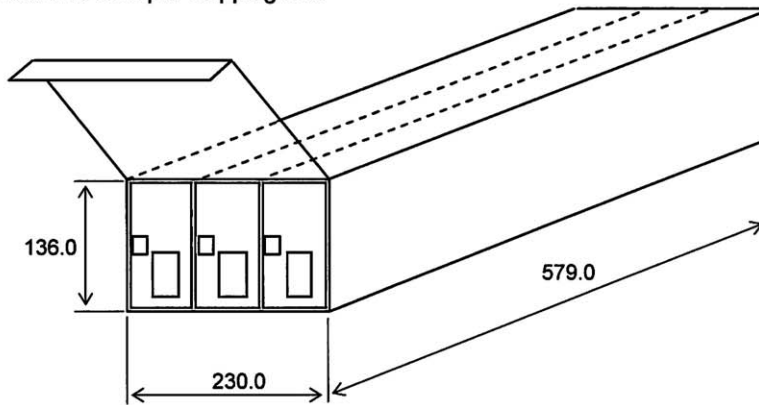


Fig. 4 Packing style

(all dimensions in mm)

2.5. Shipping style

3 unit boxes or less per shipping box



(all dimensions in mm)

2.6. Packing materials

| Item | Material |
|--------------|-----------|
| Tube | PVC |
| Stopper | PVC |
| Unit box | Cardboard |
| Shipping box | Cardboard |

3. Storage conditions

3.1. Storage environment

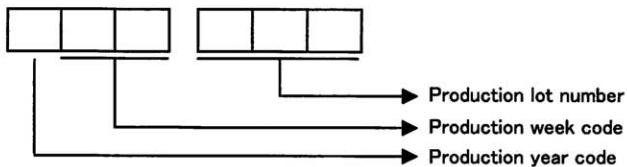
Recommended storage conditions are as follows :

- Temperature : 5 to 30°C
- Humidity : 40 to 70% RH

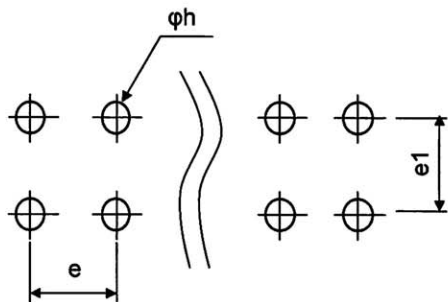
3. 2. Storage period

- Specified storage period : 1 year

4. Marking lot number



5. Footprint dimensions (Optimize footprint dimensions to the board design and soldering condition)



(all dimensions in mm)

| Package | Land pitch e | Inside land terminal dimension e1 | Land diameter φh |
|---------|--------------|-----------------------------------|------------------|
| DIP-T8 | 2.54 | 7.62 | 0.80 |
| DIP14 | 2.54 | 7.62 | 0.80 |
| DIP16 | 2.54 | 7.62 | 0.80 |
| DIP18 | 2.54 | 7.62 | 0.80 |
| DIP20 | 2.54 | 7.62 | 0.80 |
| DIP22 | 2.54 | 7.62 | 0.80 |
| DIP28 | 2.54 | 15.24 | 0.80 |

6. Soldering conditions

6. 1. Recommended temperature profile for reflow

| Process | Conditions | |
|------------|----------------|-----------|
| | Temperature | Time |
| Preheating | 120°C to 150°C | 60sec MAX |
| Soldering | 260°C ± 3°C | 12sec MAX |

(Notice) Soldering time is provided for total soldering time in case of dual wave soldering.

6. 2. 1. Notes for wave soldering

- (1) Do not use other soldering methods with wave soldering.
- (2) Recommend to clean the board to eliminate flux, solder waste, and other impurities for reliability, after soldering.
- (3) Optimize soldering condition to prevent solder bridging.

6. 3. Recommended condition for solder iron

Recommended condition for solder iron

- Solder iron temperature : 380°C or less
- Mounting time : 4sec or less

<Unit box dimensions >

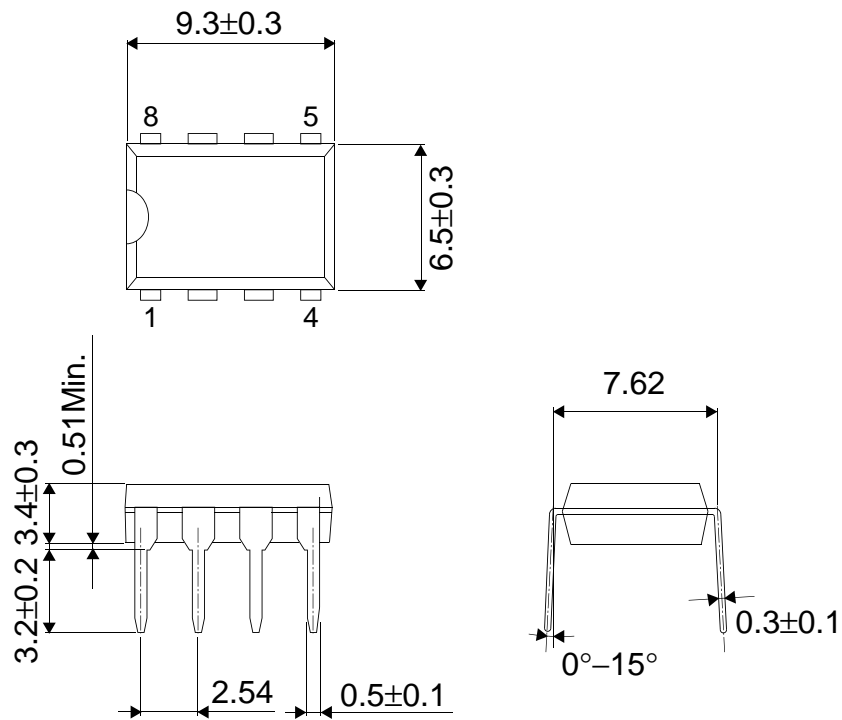
| Package | Quantity (pcs) | Unit box dimensions (all dimensions in mm) | | |
|---------|----------------|--|-----|-----|
| | | A | B | C |
| DIP-T8 | 2000 | 70 | 130 | 510 |
| DIP14 | 1000 | 70 | 130 | 510 |
| DIP16 | 1000 | 70 | 130 | 510 |
| DIP18 | 1000 | 70 | 130 | 510 |
| DIP20 | 600 | 70 | 130 | 510 |
| DIP22 | 600 | 70 | 130 | 510 |
| DIP28 | 280 | 60 | 130 | 560 |

< Dehydrated weight >

| Dehydrated weight dimensions in g |
|-----------------------------------|
| 0.39 |
| 1.06 |
| 1.10 |
| 1.27 |
| 1.49 |
| 1.72 |
| 4.20 |

Package Dimensions

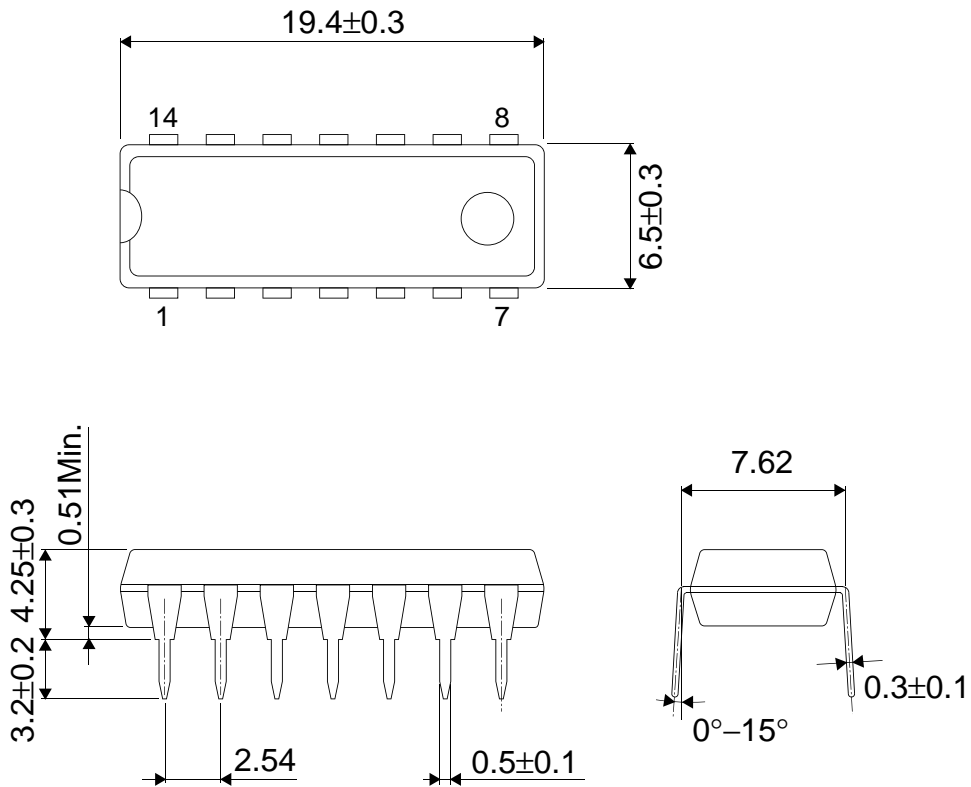
DIP-T8



(Unit : mm)

Package Dimensions

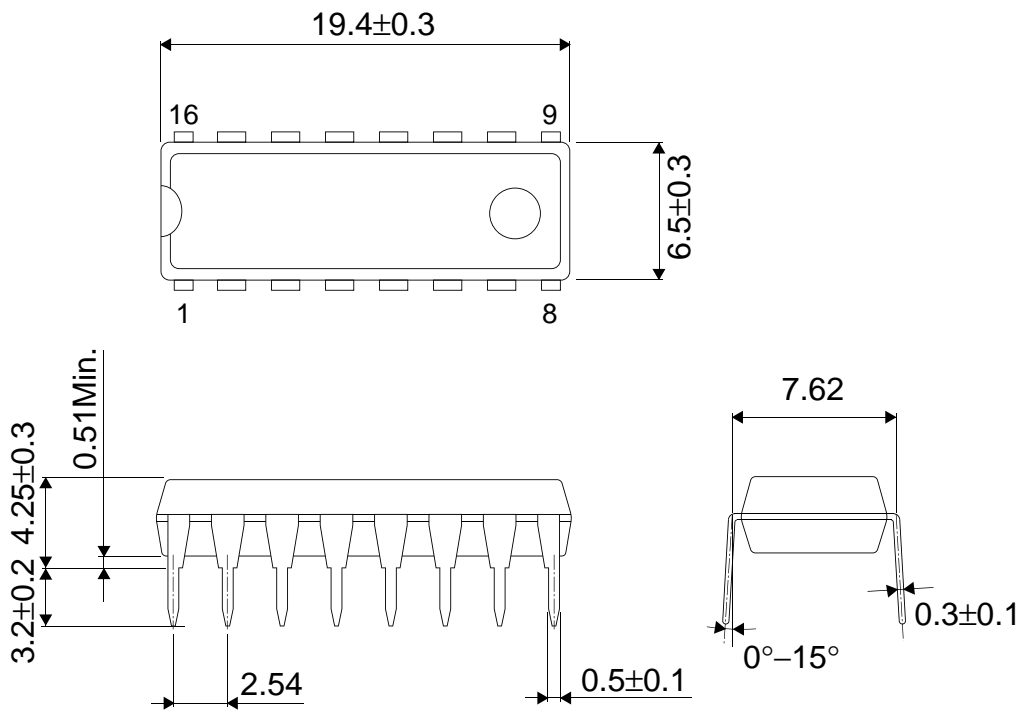
DIP14



(Unit : mm)

Package Dimensions

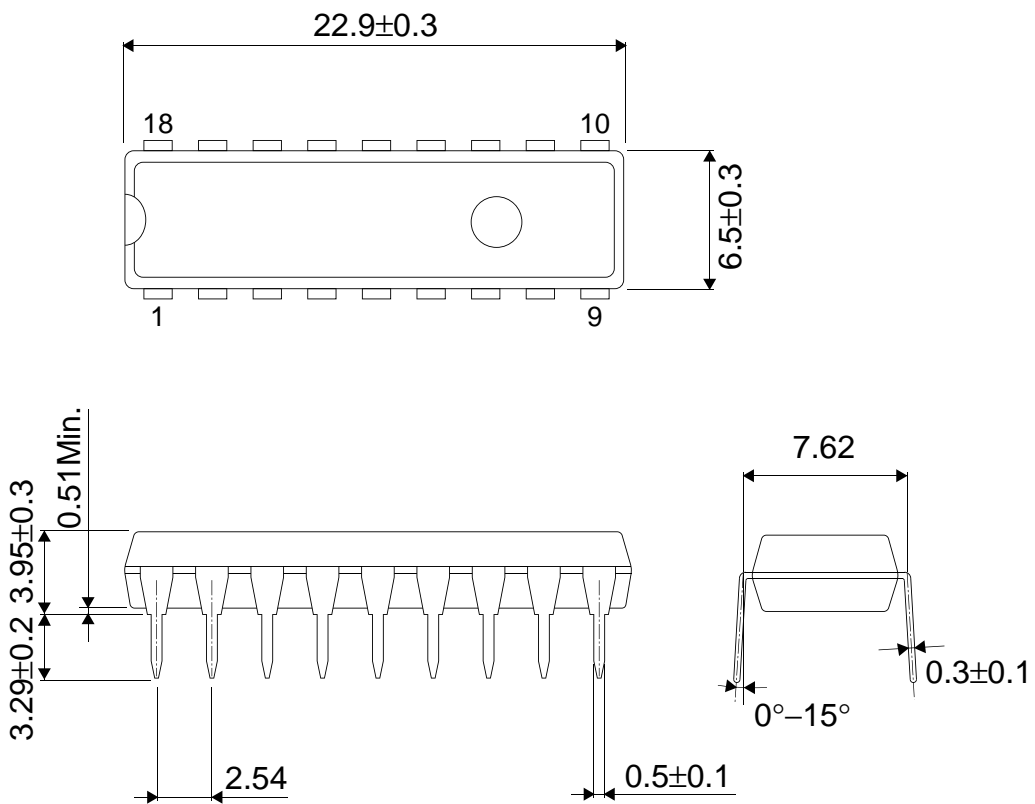
DIP16



(Unit : mm)

Package Dimensions

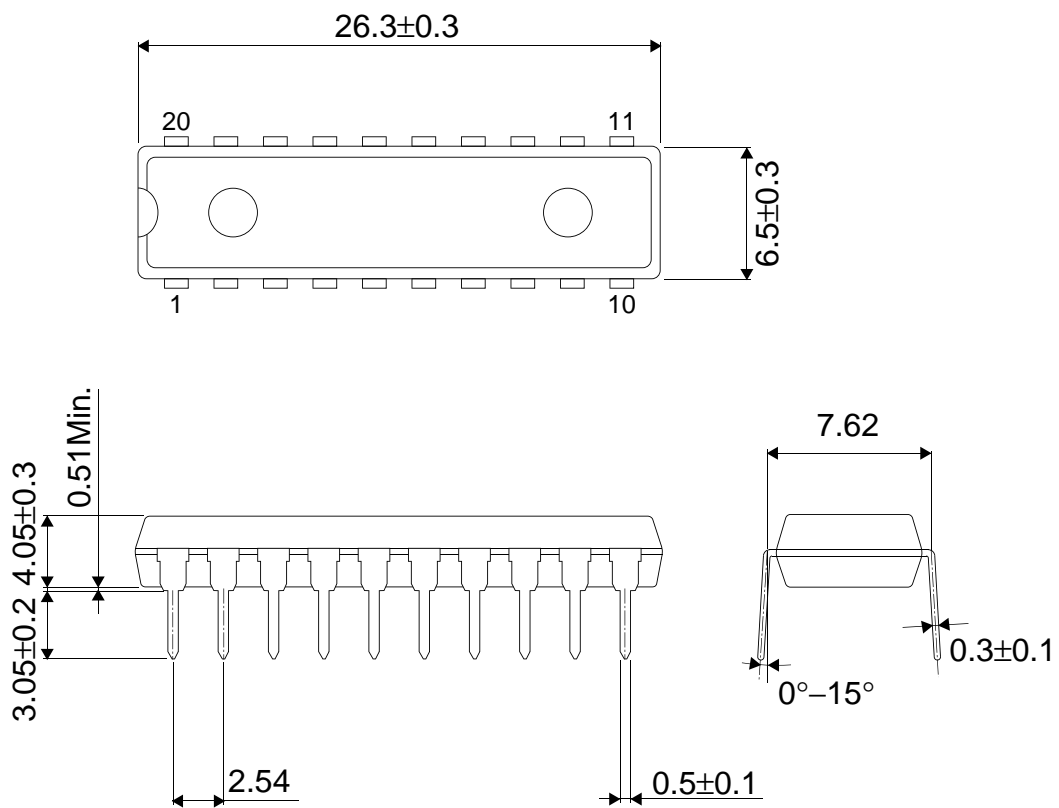
DIP18



(Unit : mm)

Package Dimensions

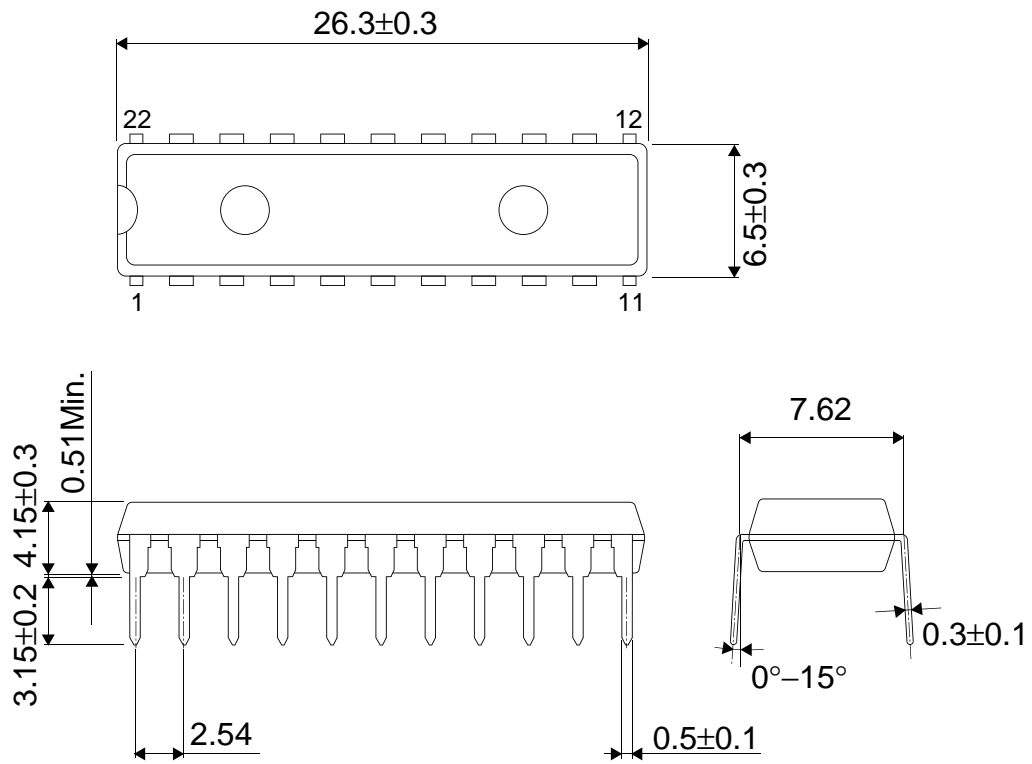
DIP20



(Unit : mm)

Package Dimensions

DIP22



(Unit : mm)

Notes

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